

# MIC5800/1

# 4/8-Bit Parallel-Input Latched Drivers

#### **Features**

- · 4.4 MHz Minimum Data Input Rate
- · High-Voltage, High-Current Sink Outputs
- · Output Transient Protection
- CMOS, PMOS, NMOS, and TTL Compatible Inputs
- · Internal Pull-Down Resistors
- · Low-Power CMOS Latches

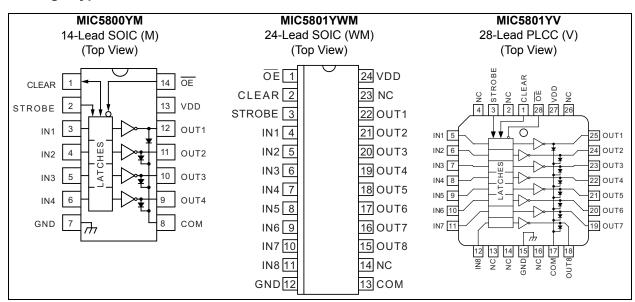
#### **General Description**

The MIC5800 and MIC5801 latched drivers are high-voltage, high-current integrated circuits comprised of four or eight CMOS data latches, a bipolar Darlington transistor driver for each latch, and CMOS control circuitry for the common CLEAR, STROBE, and OUTPUT ENABLE functions.

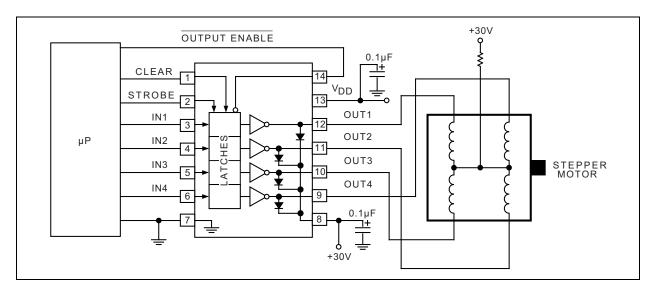
The bipolar/MOS combination provides an extremely low-power latch with maximum interface flexibility. MIC5800 contains four latched drivers; MIC5801 contains eight latched drivers.

Data input rates are greatly improved in these devices. With a 5V supply, they will typically operate at better than 5 MHz. With a 12V supply, significantly higher speeds are obtained. The CMOS inputs are compatible with standard CMOS, PMOS, and NMOS circuits. TTL or DTL circuits may require the use of appropriate pull-up resistors. The bipolar outputs are suitable for use with relays, solenoids, stepping motors, LED or incandescent displays, and other high-power loads. Both units have open-collector outputs and integral diodes for inductive load transient suppression. The output transistors are capable of sinking 500 mA and will sustain at least 50V in the OFF state. Because of limitations on package power dissipation, the simultaneous operation of all drivers at maximum rated current can only be accomplished by a reduction in duty cycle. Outputs may be connected in parallel for higher load current capability.

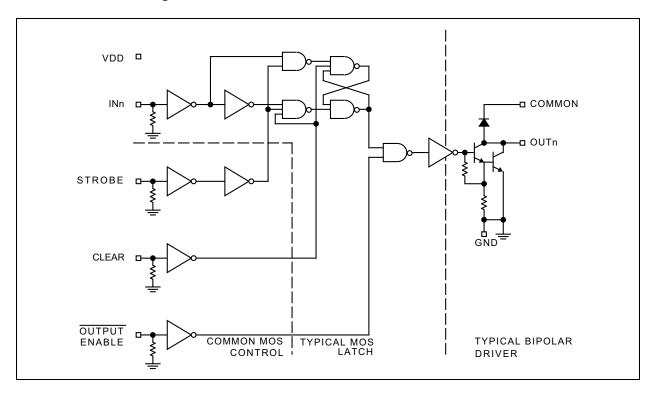
#### **Package Types**



# **Typical Application Circuit**



## **Functional Block Diagram**



#### 1.0 ELECTRICAL CHARACTERISTICS

#### **Absolute Maximum Ratings †**

Output Voltage (V <sub>CE</sub> )	+50V
Supply Voltage (V <sub>DD</sub> )	
Input Voltage Range (V <sub>IN</sub> )	
Continuous Collector Current (I <sub>C</sub> )	
ESD Rating (Note 1)	

#### **Operating Ratings ††**

† Notice: Exceeding the absolute maximum ratings may damage the device.

**†† Notice:** The device is not guaranteed to function outside its operating ratings.

**Note 1:** Microchip CMOS devices have input-static protection, but are susceptible to damage when exposed to extremely high static electrical charges.

#### **ELECTRICAL CHARACTERISTICS**

<b>Electrical Characteristics:</b> V <sub>DD</sub> = 5V, T <sub>A</sub> = +25°C, V <sub>A</sub> ≤ +85°C unless otherwise noted. Note 1							
Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions	
Output Leakers Cument		1	_	50		V <sub>CE</sub> = 50V, T <sub>A</sub> = +25°C	
Output Leakage Current	ICEX	_	_	100	μA	V <sub>CE</sub> = 50V, T <sub>A</sub> = +70°C	
		_	0.9	1.1		I <sub>C</sub> = 100 mA	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	1	1.1	1.3	V	I <sub>C</sub> = 200 mA	
Cataration voltage		1	1.3	1.6		I <sub>C</sub> = 350 mA, V <sub>DD</sub> = 7.0V	
Input Voltage (Low)	V <sub>IN(0)</sub>	1	_	1.0	V	_	
	V <sub>IN(1)</sub>	10.5	_	_		V <sub>DD</sub> = 12V	
Input Voltage (High)		8.5	_	-	V	V <sub>DD</sub> = 10V	
		3.5	_	-		V <sub>DD</sub> = 5V, Note 2	
		50	200	_		V <sub>DD</sub> = 12V	
Input Resistance	R <sub>IN</sub>	50	300	_	kΩ	V <sub>DD</sub> = 10V	
		50	600	-		V <sub>DD</sub> = 5V	
			1.0	2.0		V <sub>DD</sub> = 12V, Outputs Open	
Supply Current ON (Each Stage)	I <sub>DD(ON)</sub>	1	0.9	1.7	mA	V <sub>DD</sub> = 10V, Outputs Open	
J. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1.			0.7	1.0		V <sub>DD</sub> = 5V, Outputs Open	
Supply Current OFF		-	_	200		V <sub>DD</sub> = 12V, Outputs Open, Inputs = 0V	
(Total)	I <sub>DD(OFF)</sub>		50	100	μA	V <sub>DD</sub> = 5V, Outputs Open, Inputs = 0V	

Note 1: Specification for packaged product only.

2: Operation of these devices with standard TTL or DTL may require the use of appropriate pull-up resistors to ensure a minimum logic "1".

# **ELECTRICAL CHARACTERISTICS (CONTINUED)**

<b>Electrical Characteristics:</b> V <sub>DD</sub> = 5V, T <sub>A</sub> = +25°C, V <sub>A</sub> ≤ +85°C unless otherwise noted. Note 1								
Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions		
Clamp Diode Leakage		_	_	50		V <sub>R</sub> = 50V, T <sub>A</sub> = +25°C		
Current	<sup>I</sup> R	_	_	100	μΑ	V <sub>R</sub> = 50V, T <sub>A</sub> = +70°C		
Clamp Diode Forward Voltage	V <sub>F</sub>		1.7	2.0	V	I <sub>F</sub> = 350 mA		

- Note 1: Specification for packaged product only.
  - 2: Operation of these devices with standard TTL or DTL may require the use of appropriate pull-up resistors to ensure a minimum logic "1".

#### **TRUTH TABLE**

INI	Ctucho	Clear	/OF	OUT <sub>N</sub>		
IN <sub>N</sub>	Strobe	Clear	/OE	t – 1	t	
0	1	0	0	Х	OFF	
1	1	0	0	X	ON	
X	Х	1	X	X	OFF	
X	X	X	1	X	OFF	
X	0	0	0	ON	ON	
Х	0	0	0	OFF	OFF	

**Legend:** X = Irrelevant; t - 1 = Previous output state; t = Present output state.

Information present at an input is transferred to its latch when the STROBE is high. A high CLEAR input will set all latches to the output OFF condition regardless of the data or STROBE input levels. A high /OE will set all outputs to the off condition, regardless of any other input conditions. When the /OE is low, the outputs depend on the state of their respective latches.

## **TEMPERATURE SPECIFICATIONS**

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
Storage Temperature Range	T <sub>S</sub>	-65	_	+125	°C	_
Operating Temperature Range	T <sub>A</sub>	-40	_	+85	°C	_

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

## 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1 and Table 2-2.

TABLE 2-1: MIC5800 PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	CLEAR	Resets all latches and turns all outputs OFF (open).
2	STROBE	Input strobe pin. Loads output latches when high.
3, 4, 5, 6	IN <sub>N</sub>	Parallel inputs, 1 through 4.
7	GND	Logic and Output Ground pin.
8	COM	Transient suppression diode common cathode pin.
9, 10, 11, 12	OUT <sub>N</sub>	Parallel outputs, 4 through 1.
13	VDD	Logic Supply Voltage.
14	/OE	Output Enable. When low, outputs are active. When high, outputs are inactive and device is reset from a fault condition. An undervoltage condition emulates a high OE input.

TABLE 2-2: MIC5801 PIN FUNCTION TABLE

Pin Number SOIC	Pin Number PLCC	Pin Name	Description		
1	28	/OE	Output Enable. When low, outputs are active. When high, outputs are inactive and device is reset from a fault condition. An undervoltage condition emulates a high OE input.		
2	1	CLEAR	Resets all latches and turns all outputs OFF (open).		
3	3	STROBE	Input strobe pin. Loads output latches when high.		
4, 5, 6, 7, 8, 9, 10, 11	5, 6, 7, 8, 9, 10, 11, 12	IN <sub>N</sub>	Parallel inputs, 1 through 8.		
12	15	GND	Logic and Output Ground pin.		
13	17	COM	Transient suppression diode common cathode pin.		
14, 23	2, 4, 13, 14, 16, 26	NC	No Connection. Leave floating.		
15, 16, 17, 18, 19, 20, 21, 22	18, 19, 20, 21, 22, 23, 24, 25	OUT <sub>N</sub>	Parallel outputs, 8 through 1.		
24	27	VDD	Logic Supply Voltage.		

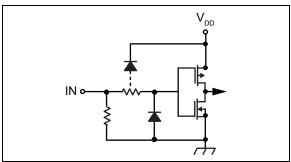


FIGURE 2-1: Typical Input.

## 3.0 TIMING

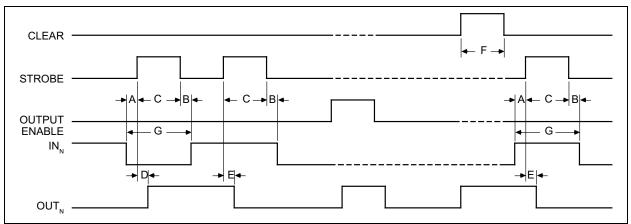


FIGURE 3-1: Timing Diagram.

TABLE 3-1: TIMING CONDITIONS

<b>Characteristics:</b> $T_A = +25$ °C; Logic levels are $V_{DD}$ and Ground; $V_{DD} = 5V$ .					
Condition	Min.	Тур.	Max.		
A. Minimum data active time before strobe enabled (data set-up time)	50 ns	_	_		
B. Minimum data active time after strobe disabled (data hold time)	50 ns	_	_		
C. Minimum strobe pulse width	125 ns	_	_		
D. Typical time between strobe activation and output on to off transition	_	500 ns	_		
E. Typical time between strobe activation and output off to on transition	_	500 ns	_		
F. Minimum clear pulse width	300 ns	_	_		
G. Minimum data pulse width	225 ns	_	_		

## 4.0 TYPICAL APPLICATIONS

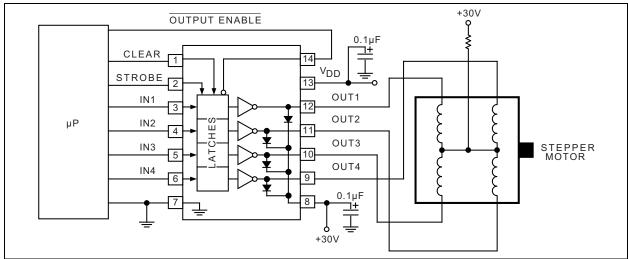
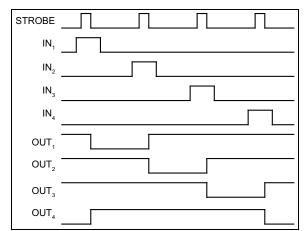
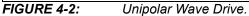


FIGURE 4-1: MIC5800 Unipolar Stepper-Motor Drive.





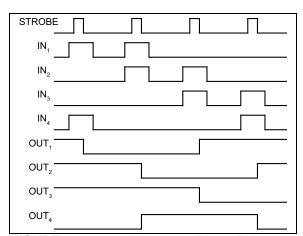


FIGURE 4-3: Unipolar 2-Phase Drive.

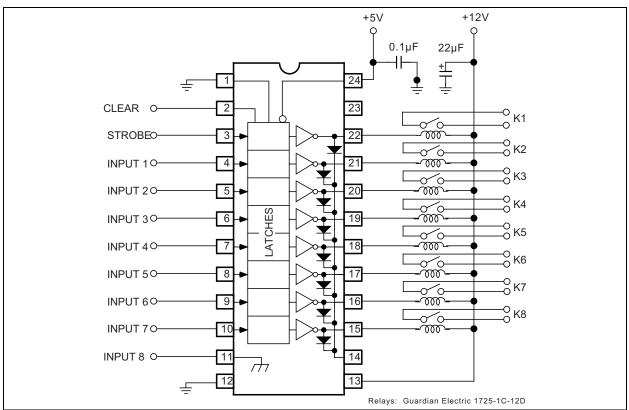


FIGURE 4-4: MIC5801 Relay Driver.

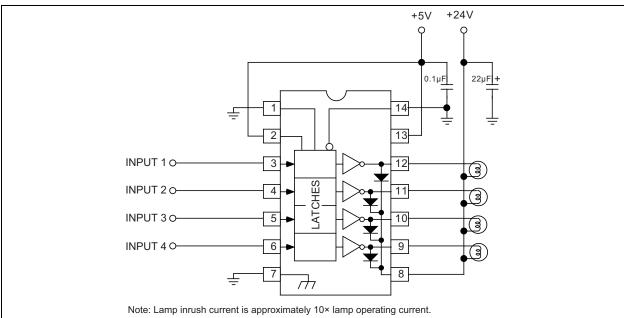
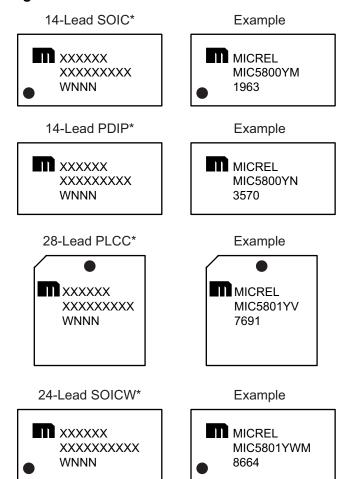


FIGURE 4-5: MIC5800 Incandescent/Halogen Lamp Driver.

#### 5.0 PACKAGING INFORMATION

#### 5.1 **Package Marking Information**



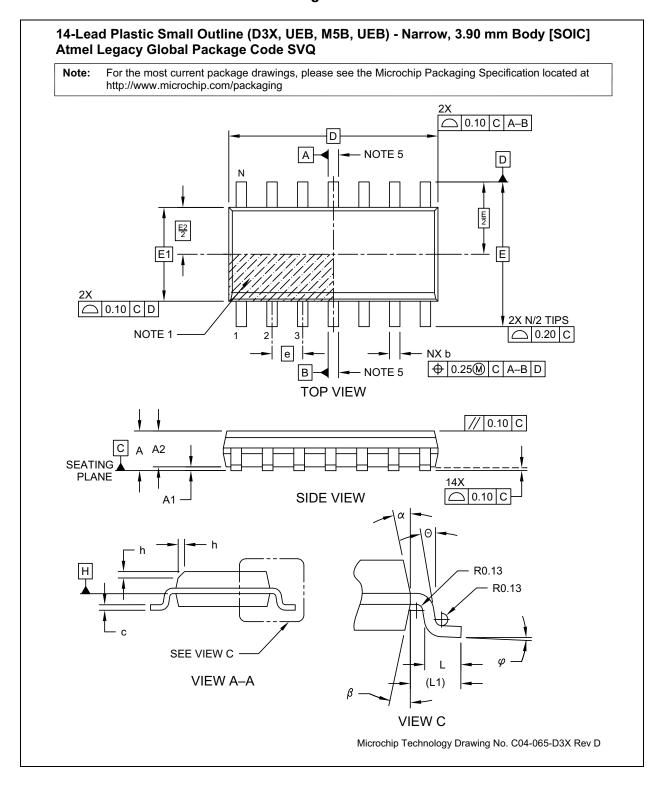
Legend: XX...X Product code or customer-specific information Υ Year code (last digit of calendar year) ΥY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code Pb-free JEDEC® designator for Matte Tin (Sn) (e3) This package is Pb-free. The Pb-free JEDEC designator (@3) can be found on the outer packaging for this package. •, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle

mark).

In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

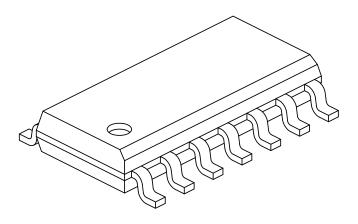
Underbar ( ) and/or Overbar ( ) symbol may not be to scale.

## 14-Lead Plastic Small Outline SOIC Package Outline and Recommended Land Pattern



# 14-Lead Plastic Small Outline (D3X, UEB, M5B, UEB) - Narrow, 3.90 mm Body [SOIC] Atmel Legacy Global Package Code SVQ

**ote:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	
Number of Pins	N		14		
Pitch	е		1.27 BSC		
Overall Height	Α	-	-	1.75	
Molded Package Thickness	A2	1.25	-	-	
Standoff §	A1	0.10	-	0.25	
Overall Width	E	6.00 BSC			
Molded Package Width	E1		3.90 BSC		
Overall Length	D		8.65 BSC		
Chamfer (Optional)	h	0.25	-	0.50	
Foot Length	L	0.40	-	1.27	
Footprint	L1		1.04 REF		
Lead Angle	Θ	0°	-	-	
Foot Angle	φ	0°	-	8°	
Lead Thickness	С	0.10	-	0.25	
Lead Width	b	0.31	-	0.51	
Mold Draft Angle Top	α	5°	=	15°	
Mold Draft Angle Bottom	β	5°	-	15°	

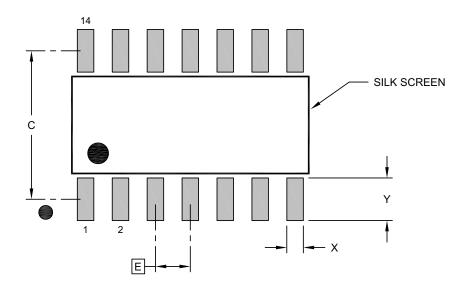
#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.
- 5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-065-D3X Rev D Sheet 2 of 2

# 14-Lead Plastic Small Outline (D3X, UEB, M5B, UEB) - Narrow, 3.90 mm Body [SOIC] Atmel Legacy Global Package Code SVQ

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



#### RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	Dimension Limits			MAX
Contact Pitch	Е		1.27 BSC	
Contact Pad Spacing	С		5.40	
Contact Pad Width (X14)	Х			0.60
Contact Pad Length (X14)	Y			1.55

#### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M  $\,$ 

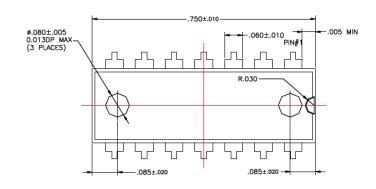
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

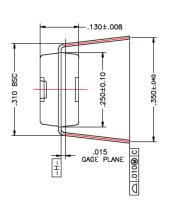
Microchip Technology Drawing No. C04-2065-D3X Rev D

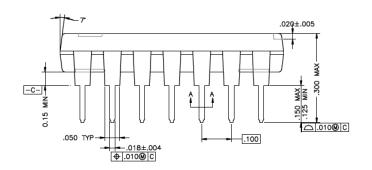
# 14-Lead PDIP Package Outline and Recommended Land Pattern

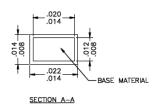
# TITLE 14 LEAD PDIP PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

DRAWING #	PDIP-14LD-PL-1	UNIT	INCH
LEAD FRAME	Copper	LEAD FINISH	Matte Tin



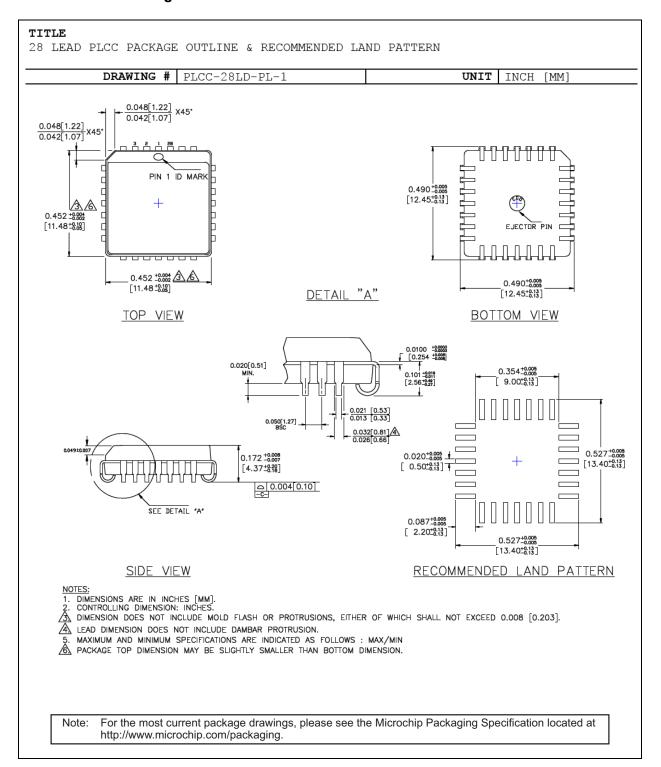




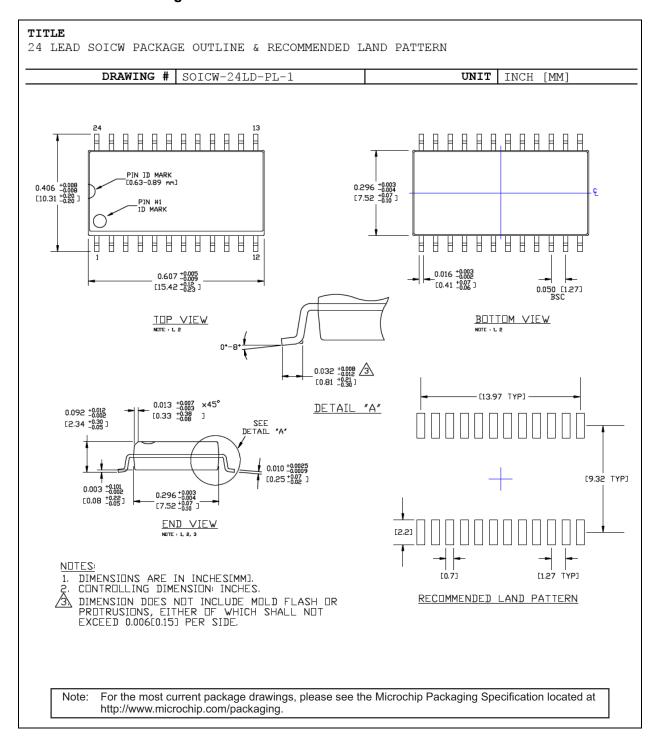


Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

#### 28-Lead PLCC Package Outline and Recommended Land Pattern



#### 24-Lead SOICW Package Outline and Recommended Land Pattern



# MIC5800/1

NOTES:

# APPENDIX A: REVISION HISTORY

# Revision A (April 2019)

- Converted Micrel document MIC5800/1 to Microchip data sheet template DS20006184A.
- Minor grammatical text changes throughout.

# MIC5800/1

NOTES:

# PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

				Example	es:	
<b>Device</b> Part No.	<b>X</b> Junction Temp. Range	<u>XX</u> Package	- <u>XX</u> Media Type	a) MIC58	00YM:	MIC5800, –40°C to +85°C Temperature Range, 14-Lead SOIC, 54/Tube
Device:	C	-Bit Parallel-Input, Hig Current Latched Driver	0,0	b) MIC58	00YM-TR:	MIC5800, -40°C to +85°C Temperature Range, 14-Lead SOIC, 2,500/Reel
		B-Bit Parallel-Input, Hig Current Latched Driver		c) MIC58	00YN:	MIC5800, –40°C to +85°C Temperature Range, 14-Lead PDIP, 25/Tube
Junction Temperature Range:	Y = -40°C	to +85°C, Industrial		d) MIC58	01YV:	MIC5801, -40°C to +85°C Temperature Range, 28-Lead PLCC, 38/Tube
Package:	N = 14-Lea V = 28-Lea	d SOIC (MIC5800) d PDIP (MIC5800) d PLCC (MIC5801)		e) MIC58	01YV-TR:	MIC5801, -40°C to +85°C Temperature Range, 28-Lead PLCC, 750/Reel
	<pre>WM = 24-Lea  <blank>= 54/Tube</blank></pre>	d Wide SOIC (MIC580 e (M, MIC5800)	11)	f) MIC580	D1YWM:	MIC5801, -40°C to +85°C Temperature Range, 24-Lead Wide SOIC, 31/Tube
Media Type:		e (V, MIC5801)		g) MIC58	01YWM-TR:	MIC5801, -40°C to +85°C Temperature Range, 24-Lead Wide SOIC, 1,000/Reel
		Reel (M, MIC5800)		Note 1:	catalog part nu used for orderi the device pac	identifier only appears in the mber description. This identifier is ng purposes and is not printed on kage. Check with your Microchip r package availability with the option.

# MIC5800/1

NOTES:

#### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
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